

WHAT IS CLAIMED IS:

1 1. A method of manufacturing an electromagnetic wave shielding filter, the method
2 comprising:

3 preparing a metal plate for plating;

4 forming an insulating layer on an upper surface of the metal plate, the insulating layer
5 having a mesh pattern;

6 forming a plating layer on a remaining upper surface of the metal plate on which the
7 insulating layer is not formed;

8 arranging an adhesive film on the metal plate having the insulating layer and the plating
9 layer;

10 adhering the adhesive film to upper surfaces of the insulating layer and the plating layer;

11 and

12 separating the adhesive film from the metal plate so that the plating layer is adhered to a
13 lower surface of the adhesive film, the plating layer being in the form of a mesh.

1 2. The method according to claim 1, wherein the metal plate comprises an alloy
2 selected from at least one of SUS, a titanium alloy, a nickel alloy, a copper alloy, and an iron alloy,
3 the metal plate acting as a seed layer for electrolytic plating.

1 3. The method according to claim 1, wherein the insulating layer is formed by oxide

2 coating.

1 4. The method according to claim 1, wherein the plating layer comprises at least one
2 of copper or silver.

1 5. The method according to claim 1, wherein the adhesive film comprises polyethylene
2 terephthalate (PET).

1 6. The method according to claim 1, wherein the adhesive film comprises a polymer
2 film.

1 7. The method according to claim 1, wherein a binding force of the plating layer to the
2 adhesive film is stronger than a binding force of the plating layer to the metal plate.

1 8. A method of manufacturing an electromagnetic wave shielding filter, the method
2 comprising:

3 preparing a metal plate for plating;

4 forming a photoresist layer on an upper surface of the metal plate, the photoresist layer
5 having a mesh pattern;

6 forming a plating layer on a remaining upper surface of the metal plate on which the
7 photoresist layer is not formed;

8 removing the photoresist layer from the metal plate;
9 arranging an adhesive film on the metal plate having the plating layer;
10 adhering the adhesive film to an upper surface of the plating layer; and
11 separating the adhesive film from the metal plate so that the plating layer is adhered to a
12 lower surface of the adhesive film, the plating layer being in the form of a mesh.

1 9. The method according to claim 8, wherein the metal plate comprises an alloy
2 selected from at least one of SUS, a titanium alloy, a nickel alloy, a copper alloy, and an iron alloy,
3 the metal plate acting as a seed layer for electrolytic plating.

1 10. The method according to claim 8, wherein the adhesive film comprises a polymer
2 film.

1 11. A method of manufacturing an electromagnetic wave shielding filter, the method
2 comprising:
3 preparing a substrate;
4 adhering a metal foil to an upper surface of the substrate;
5 forming a photoresist layer on an upper surface of the metal foil, the photoresist layer
6 having a mesh pattern;
7 forming a plating layer on a remaining upper surface of the metal foil on which the
8 photoresist layer is not formed;

9 removing the photoresist layer from the metal foil;
10 arranging an adhesive film on the metal foil having the plating layer;
11 adhering the adhesive film to an upper surface of the plating layer; and
12 separating the adhesive film from the metal foil so that the plating layer is adhered to a
13 lower surface of the adhesive film, the plating layer being in the form of a mesh.

1 12. The method according to claim 11, wherein the metal plate comprises an alloy
2 selected from at least one of SUS, a titanium alloy, a nickel alloy, a copper alloy, and an iron alloy,
3 the metal plate acting as a seed layer for electrolytic plating.

1 13. The method according to claim 11, wherein the plating layer comprises at least one
2 of copper or silver.

1 14. The method according to claim 11, further comprising blackening the surface of the
2 plating layer to increase contrast, after forming the plating layer.

1 15. The method according to claim 11, wherein the adhesive film comprises PET.

1 16. The method according to claim 11, wherein a binding force of the plating layer to
2 the adhesive film is stronger than a binding force of the plating layer to the substrate or the metal
3 foil.

1 17. The method according to claim 11, wherein the adhesive film comprises a polymer
2 film.

1 18. An electromagnetic wave shielding filter, manufactured by preparing a substrate,
2 forming a meshed plating layer on an upper surface of the substrate, adhering an adhesive film to
3 an upper surface of the plating layer, and separating the adhesive film from the substrate so that
4 the plating layer is adhered to a lower surface of the adhesive film.

1 19. The electromagnetic wave shielding filter according to claim 18, wherein the
2 substrate is a metal plate arranged to act as a seed layer for electrolytic plating.

1 20. The electromagnetic wave shielding filter according to claim 18, wherein the metal
2 plate comprises an alloy selected from at least one of SUS, a titanium alloy, a nickel alloy, a
3 copper alloy, or an iron alloy.

1 21. The electromagnetic wave shielding filter according to claim 18, wherein the plating
2 layer comprises at least one of copper or silver.

1 22. The electromagnetic wave shielding filter according to claim 18, wherein the
2 surface of the plating layer is blackened.

1 23. The electromagnetic wave shielding filter according to claim 18, wherein the
2 adhesive film comprises PET.

1 24. The electromagnetic wave shielding filter according to claim 18, wherein the
2 adhesive film comprises a polymer film.

1 25. The electromagnetic wave shielding filter according to claim 18, wherein a
2 transparent layer containing an acrylic solid is further arranged on the upper surface of the meshed
3 plating layer to cover voids in the meshed plating layer.

1 26. The electromagnetic wave shielding filter according to claim 25, wherein the
2 transparent layer comprises at least one of an acrylate or a butyl carbitol.

1 27. The electromagnetic wave shielding filter according to claim 25, wherein the
2 transparent layer comprises 10% or less of an adhesive.